

SOT1915-1

FBGA525, fine-pitch ball grid array package; 525 terminals,
0.8 mm pitch, 19 mm x 19 mm x 2.47 mm body

22 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA525
Mounting method type	S (surface mount)
Issue date	24-01-2017
Manufacturer package code	98ASA01060D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	19	-	mm
package width	-	19	-	mm
seated height	-	2.47	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	525	-	



2 Package outline

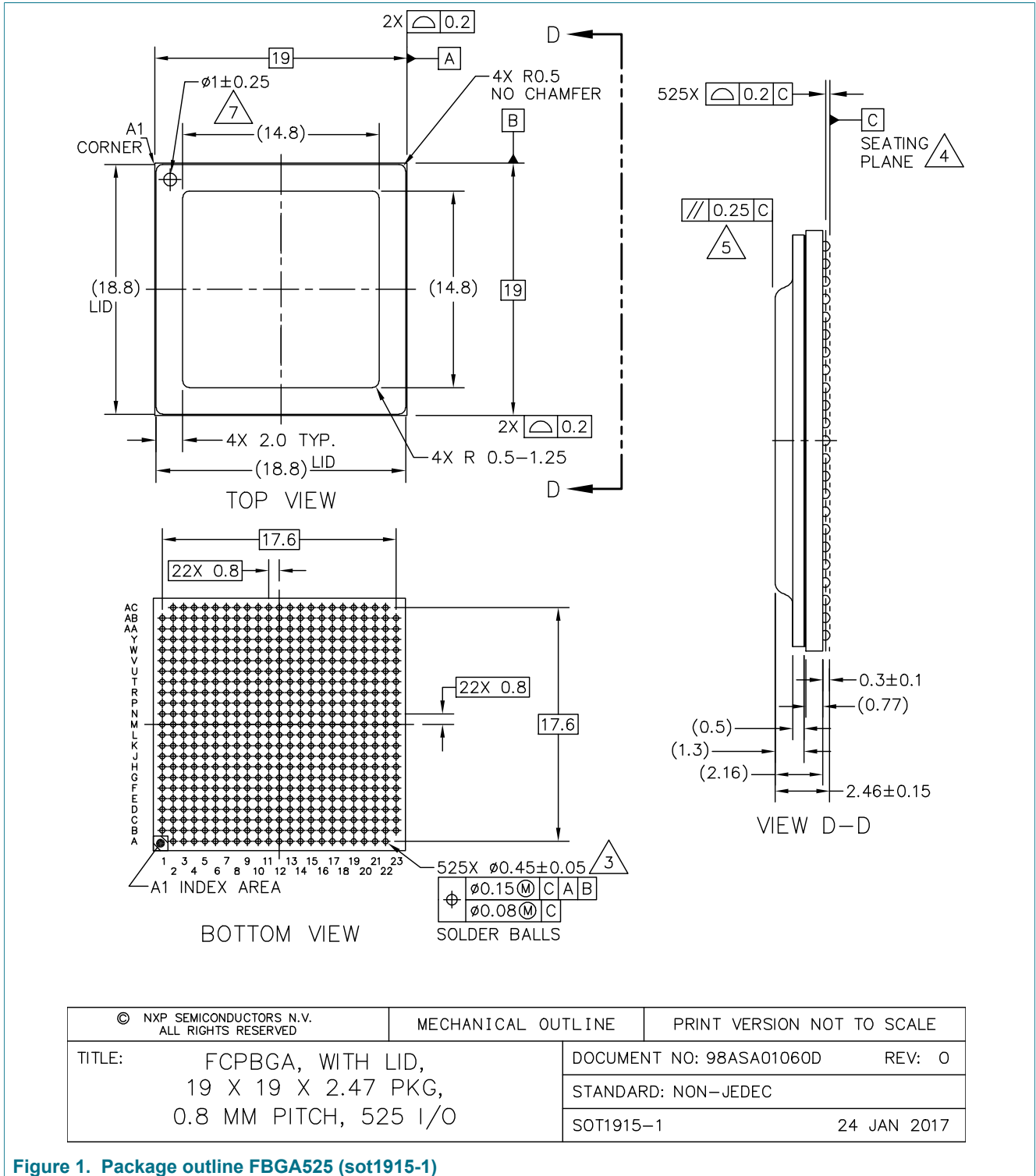


Figure 1. Package outline FBGA525 (sot1915-1)

FBGA525, fine-pitch ball grid array package; 525 terminals, 0.8 mm pitch, 19 mm x 19 mm x 2.47 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN THE FOOT AREA.
8. 19.15MM MAXIMUM PACKAGE ASSEMBLY (LID + LAMINATE) X AND Y.
9. LID OVERHANG ON SUBSTRATE NOT TO EXCEED 0.1MM.

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TITLE: FCPBGA, WITH LID, 19 X 19 X 2.47 PKG, 0.8 MM PITCH, 525 I/O	DOCUMENT NO: 98ASA01060D	REV: 0
	STANDARD: NON-JEDEC	
	SOT1915-1	24 JAN 2017

Figure 2. Package outline note FBGA525 (sot1915-1)

3 Legal information

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